

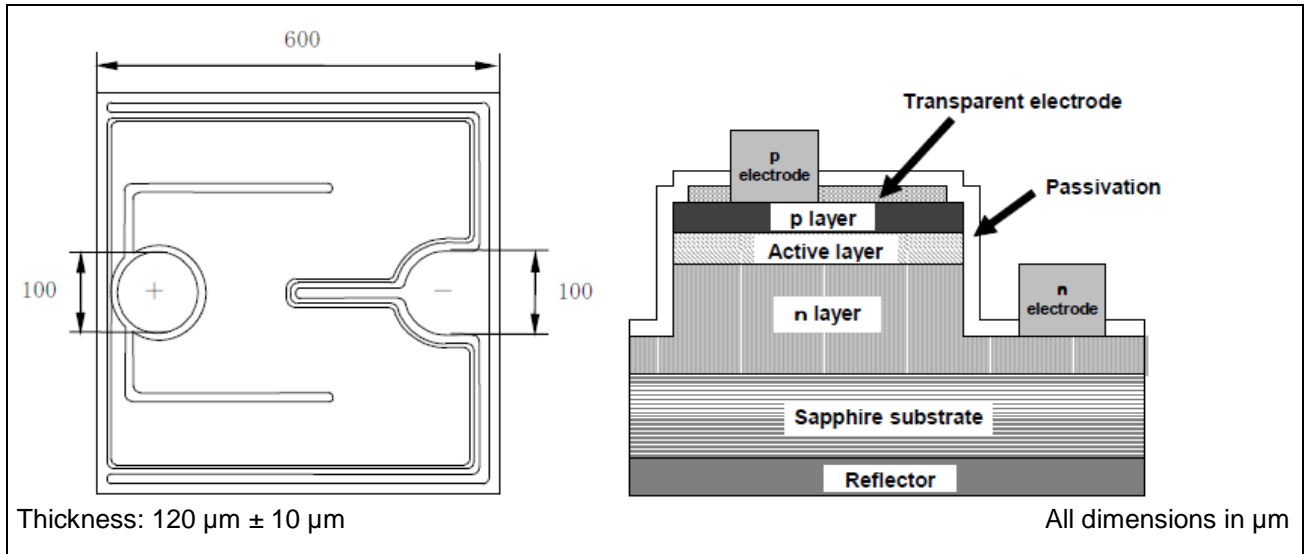


C365-3SRA1

TECHNICAL DATA

UV LED high power chip die, 365nm

Drawing



Storage Conditions

Item	Value
Storage time	3 Months
Storage Temperature	5 ... +35 °C
Storage Humidity	45 ...85 %

Specifications (If=100mA, Ta=25°C)

Item	Symbol	Min.	Typ.	Max.	Unit
Electrical Specification					
Forward Voltage *1	U _F	3.2	3.6	4.2	V
Reverse Current	I _R			10.0	μA
Optical Specification					
Optical Power	P _O	5	-	10	mW
Peak Wavelength *2	λ _P	363	-	370	nm
Spectral Half Width (FWHM)	Δλ		15		nm

* measurement tolerance is ± 0.2 V, ± 2 nm

Device Materials

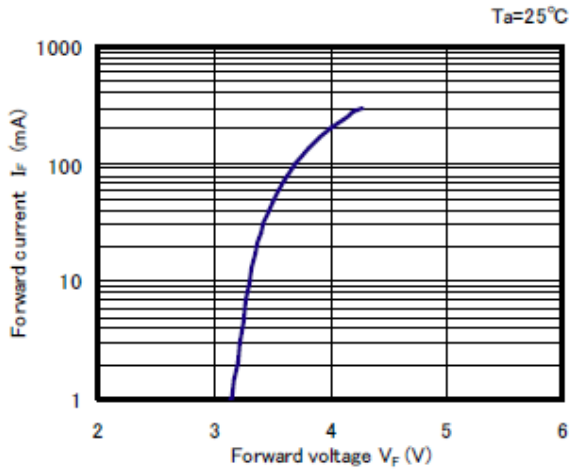
Item	Material
Wafer material	GaN based on Sapphire Substrate
Electrodes	n-contact Au p-contact Au

C365-3SRA1 is RoHS compliant

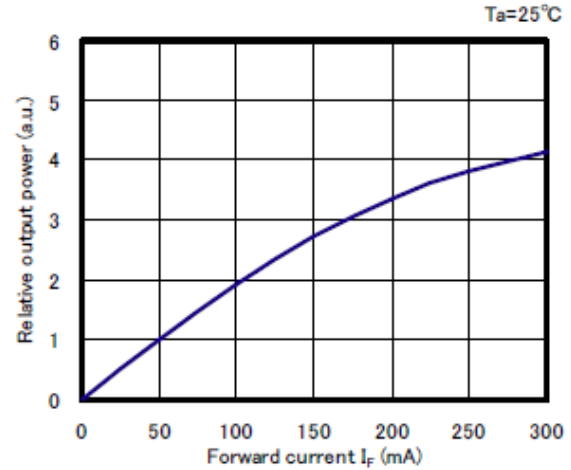


Typical Performance Curves

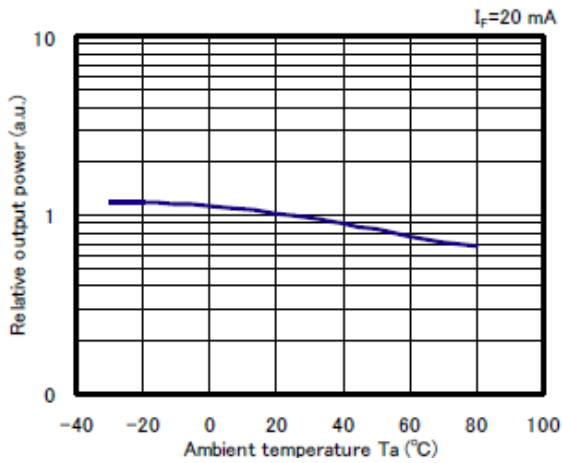
forward voltage vs. forward current:



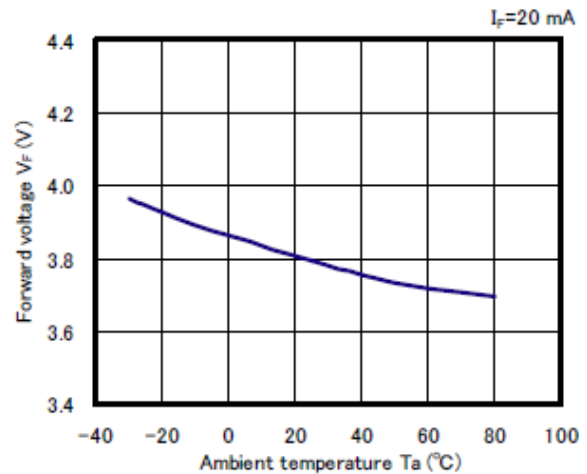
forward voltage vs. relative output power:



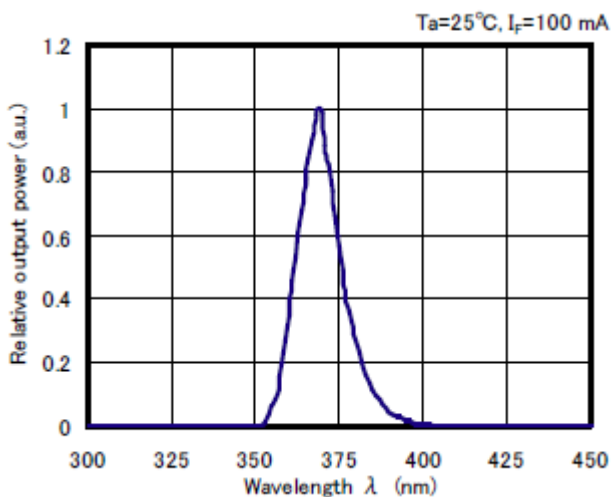
ambient temperature vs. relative output power:



ambient temperature vs. forward voltage:



spectrum:

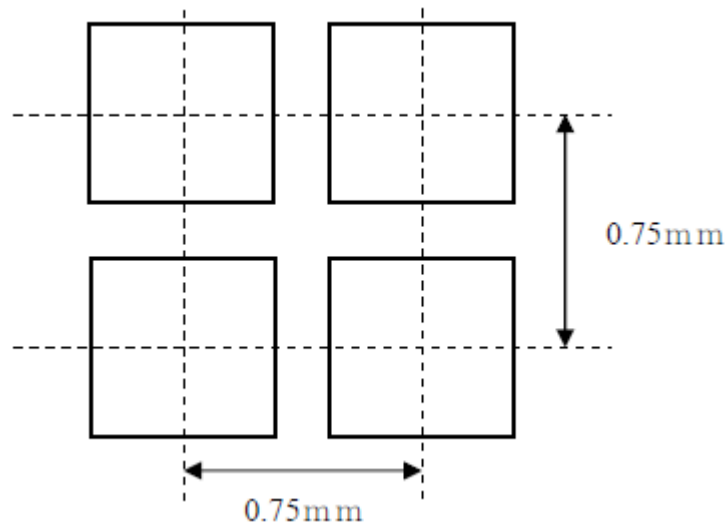


*above measurements derive from chip die packaged into resin mold LED package



Configuration

Chips are arranged on 200x200 mm adhesive sheet at 0,75mm pitch



Precaution for Use

1. Static Electricity

- The LED chip dies are very sensitive to Static Electricity and surge voltage. So it is recommended that a wrist band or an anti-electrostatic glove be used when handling the chips.
- All devices, equipment and machinery must be grounded properly. It is recommended that precautions should be taken against surge voltage to the equipment that mounts the chips.



2. Heat Generation

- Thermal design of the end product is of paramount importance. Please consider the heat generation of the chip when making the system design. The coefficient of temperature increase per input electric power is affected by the thermal resistance of the circuit board and density of chip placement on the board, as well as other components. It is necessary to avoid intense heat generation and operate within the maximum ratings given in the specification.
- The operating current should be decided after considering the ambient maximum temperature of the chip dies.